



**有铅**

Sn50/Pb50 SnPbBi

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1 0.4mm

2 12

3

4

5

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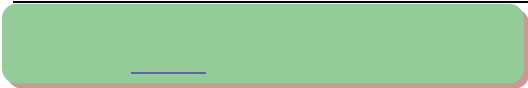
6 PCB

7 ICT

8 Paste in hole

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		ROL1	J-STD-004
		0.2wt%	
(SIR)		1 10 <sup>13</sup>	25mil
		1 10 <sup>12</sup>	40 90%RH 96Hrs
		1 10 <sup>5</sup>	
			IPC-TM-650
			IPC-TM-650
			In house
		85~91wt% ± 0.5	
		9~15wt% ± 0.5	
		200 Pa.s ± 10% Malcolm (10rpm, 2 )	T3, 90% metal for printing
		80 Pa.s ± 10% Malcolm (10rpm, 2 )	T4, 87% metal for syringe
		0.55 ± 0.05	In house
		90%	Copper plate (Sn63, 90% metal)
			J-STD-005
			In house
Vs	48gF	0	IPC-TM-650 ± 5%
	56gF	2	
	68gF	4	
	44gF	8	
		12	In house
			0~10



1

T3 mesh -325/+500 25~45 m

Fine pitch

2

1) “ ”

0~10

200

4

2)

3

1 ;

3



有铅免洗

0.4mm

0.12mm



有铅免洗

80%

	60 ~ 90HS
	45 <sup>0</sup> ~ 60 <sup>0</sup>
	2 ~ 4 10 <sup>5</sup> pa
	20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec
	25 ± 3 40 ~ 70%



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PCB

PCB

A5

200g

B5

300g

A4

400g

4

4

5

6

此有铅



500g

PE

20

35



0 ~10

- 
- 

0

6



MSDS

